**In the Claims:**

1. (Currently Amended) A method of wedge-bonding wires in the manufacture of electronic devices, wherein:

a reversible bonding tool is used having a mount that engages an elongated shank in a first position between opposite ends of the shank, each end including a wedge-bonding tip ~~at opposite ends of the tool~~,

and, after using the wedge-bonding tip at one end for bonding wires, the ~~tool~~ shank is reversed and engaged by the mount in second position between opposite ends of the shank to use the wedge-bonding tip at the opposite end for bonding further wires.

2. (Currently Amendedl) A method according to Claim 1, wherein the ~~bonding tool comprises a~~ shank [[of]] is made of tungsten carbide ~~having the wedge-bonding tips at opposite ends of the shank~~.

3. (Previously Presented) A method according to Claim 1, wherein the wires comprise aluminum or gold and are ultra-sonically bonded using a transducer coupled to the tool.

4-12. (Cancelled)

13. (New) A method according to Claim 1, wherein the shank has the same cross-section at the first and second positions.

14. (New) A method according to Claim 1, wherein the shank includes one or more guide holes for feeding the wires to the wedge-bonding tips.

15. (New) A method according to Claim 14, wherein the one or more guide holes includes separate guide holes extending obliquely through each end of the shank.

16. (New) A method according to Claim 14, wherein the one or more guide holes includes a capillary bore that extends from end to end through the length of the shank.